



## Development of Edible Packaging Materials Containing Food Waste Products

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### Message from the Guest Editor

The development of edible films and coatings has seen remarkable growth in recent decades and is expected to have an important impact on the quality of food products in the following years. This phenomenon is attributed to the increasing knowledge of edible packaging materials and coating technology, as well as new food applications in this area. Edible packaging is used in order to reduce petroleum-based packaging materials and can play a role as an eco-friendly biodegradable package or a protective coating on the food surface. Many bio-based polymers have been used in the production of edible films and coatings; however, novel sources and novel processing techniques are a subject of great interest to many research teams. New film-forming materials such as plant residues or flours show their protective effectiveness and suitability in various types of foods. Plant residues are an easily available and low cost materials of edible packaging which also provide an excellent source of nutrients. Therefore, this Special Issue aims to cover the latest advances and applications of edible packaging materials based on or containing waste products from the agri-food industry.





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## Message from the Editor-in-Chief

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